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APPLICATION NO.	FILING DATE	FIRST NAMED INVENTOR	ATTORNEY DOCKET NO.	CONFIRMATION NO.
09/925,740	08/10/2001	Takuya Yamamoto	108384-00030	6658
6449	7590	06/09/2005	EXAMINER	
ROTHWELL, FIGG, ERNST & MANBECK, P.C. 1425 K STREET, N.W. SUITE 800 WASHINGTON, DC 20005			NGUYEN, KHIEM D	
			ART UNIT	PAPER NUMBER
			2823	

DATE MAILED: 06/09/2005

Please find below and/or attached an Office communication concerning this application or proceeding.

Office Action Summary

Application No.

09/925,740

Applicant(s)

YAMAMOTO ET AL.

Examiner

Khiem D. Nguyen

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-- The MAILING DATE of this communication appears on the cover sheet with the correspondence address --

Period for Reply

A SHORTENED STATUTORY PERIOD FOR REPLY IS SET TO EXPIRE 3 MONTH(S) FROM THE MAILING DATE OF THIS COMMUNICATION.

- Extensions of time may be available under the provisions of 37 CFR 1.136(a). In no event, however, may a reply be timely filed after SIX (6) MONTHS from the mailing date of this communication.
- If the period for reply specified above is less than thirty (30) days, a reply within the statutory minimum of thirty (30) days will be considered timely.
- If NO period for reply is specified above, the maximum statutory period will apply and will expire SIX (6) MONTHS from the mailing date of this communication.
- Failure to reply within the set or extended period for reply will, by statute, cause the application to become ABANDONED (35 U.S.C. § 133). Any reply received by the Office later than three months after the mailing date of this communication, even if timely filed, may reduce any earned patent term adjustment. See 37 CFR 1.704(b).

Status

- 1) ☒ Responsive to communication(s) filed on 24 March 2005.
- 2a) ☐ This action is **FINAL**. 2b) ☒ This action is non-final.
- 3) ☐ Since this application is in condition for allowance except for formal matters, prosecution as to the merits is closed in accordance with the practice under *Ex parte Quayle*, 1935 C.D. 11, 453 O.G. 213.

Disposition of Claims

- 4) ☒ Claim(s) 5-22 is/are pending in the application.
- 4a) Of the above claim(s) _____ is/are withdrawn from consideration.
- 5) ☐ Claim(s) _____ is/are allowed.
- 6) ☒ Claim(s) 5-22 is/are rejected.
- 7) ☐ Claim(s) _____ is/are objected to.
- 8) ☐ Claim(s) _____ are subject to restriction and/or election requirement.

Application Papers

- 9) ☐ The specification is objected to by the Examiner.
- 10) ☒ The drawing(s) filed on 10 August 2001 is/are: a) ☒ accepted or b) ☐ objected to by the Examiner.
Applicant may not request that any objection to the drawing(s) be held in abeyance. See 37 CFR 1.85(a).
Replacement drawing sheet(s) including the correction is required if the drawing(s) is objected to. See 37 CFR 1.121(d).
- 11) ☐ The oath or declaration is objected to by the Examiner. Note the attached Office Action or form PTO-152.

Priority under 35 U.S.C. § 119

- 12) ☒ Acknowledgment is made of a claim for foreign priority under 35 U.S.C. § 119(a)-(d) or (f).
- a) ☒ All b) ☐ Some * c) ☐ None of:
1. ☒ Certified copies of the priority documents have been received.
2. ☐ Certified copies of the priority documents have been received in Application No. _____.
3. ☐ Copies of the certified copies of the priority documents have been received in this National Stage application from the International Bureau (PCT Rule 17.2(a)).

* See the attached detailed Office action for a list of the certified copies not received.

Attachment(s)

- 1) ☒ Notice of References Cited (PTO-892)
- 2) ☐ Notice of Draftsperson's Patent Drawing Review (PTO-948)
- 3) ☐ Information Disclosure Statement(s) (PTO-1449 or PTO/SB/08)
Paper No(s)/Mail Date _____
- 4) ☐ Interview Summary (PTO-413)
Paper No(s)/Mail Date _____
- 5) ☐ Notice of Informal Patent Application (PTO-152)
- 6) ☐ Other: _____

DETAILED ACTION

The non-final rejection as set forth in paper No. (052704) mailed June 02nd, 2004 is withdrawn in response to applicants' amendments. A new rejection is made as set forth in this Office Action. Claims (5-22) are pending in the application.

Claim Rejections - 35 USC § 102

The following is a quotation of the appropriate paragraphs of 35 U.S.C. 102 that form the basis for the rejections under this section made in this Office action:

A person shall be entitled to a patent unless –

(b) the invention was patented or described in a printed publication in this or a foreign country or in public use or on sale in this country, more than one year prior to the date of application for patent in the United States.

Claims 5-7, 10-13, 16-19, and 22 are rejected under 35 U.S.C. 102(b) as being anticipated by Saida et al. (U.S. Patent 5,674,611).

In re claim 5, Saida discloses a process for producing a copper clad laminate comprising, providing an insulation layer constituent material having a first and a second side (col. 1, lines 10-45 and col. 5, lines 43-60), coating the first side with a first copper foil of a first thickness (12 μm , col. 5, lines 9-16), coating the second side with a second copper foil of a second thickness (35 μm , col. 6, lines 15-32) to produce an insulation layer constituent material, first copper foil and second copper foil assembly, wherein the thickness of the second foil is greater than the thickness of the first foil (col. 5, lines 9-16 and col. 6, lines 15-32), hot pressing the assembly to produce the laminate (col. 5, lines 43-52), wherein the first copper foil is not recrystallized during the hot pressing (col. 1, lines 10-45), and wherein the second copper foil is recrystallized during the hot pressing (col. 1, lines 46-54).

In re claim 6, **Saida** discloses that the thickness of the second foil (35 μm , col. 6, lines 15-32) is four times or less than the thickness of the first foil (12 μm , col. 5, lines 9-16).

In re claim 7, **Saida** discloses that the insulation layer constituent material is a resin (col. 4, lines 57-64).

In re claim 10, **Saida** discloses that, after hot pressing the Young's modulus of the first copper foil is 1.1 times more than the Young's modulus of the second copper foil (col. 5, lines 9-52).

In re claim 11, **Saida** discloses a process for producing a copper clad laminate comprising, providing an insulation layer constituent material having a first and a second side (col. 1, lines 10-45 and col. 5, lines 43-60), coating the first side with a first copper foil of a first thickness (12 μm , col. 5, lines 9-16), coating the second side with a second copper foil of a second thickness (35 μm , col. 5, lines 43-52) to produce an insulation layer constituent material, first copper foil and second copper foil assembly (col. 5, lines 43-52), wherein the thickness of the second foil is greater than the thickness of the first foil (col. 5, lines 9-16 and col. 5, lines 43-52), hot pressing the assembly to produce the laminate (col. 5, lines 43-52), wherein the first and second copper foils are recrystallized during the hot pressing, wherein the second copper foil is more recrystallized than the first copper foil (col. 1, lines 10-54).

In re claim 12, **Saida** discloses that the thickness of the second foil (35 μm , col. 5, lines 43-52) is four times or less than the thickness of the first foil (12 μm , col. 5, lines 9-16).

In re claim 13, **Saida** discloses that the insulation layer constituent material is a resin (col. 4, lines 57-64).

In re claim 16, **Saida** discloses that, after hot pressing the Young's modulus of the first copper foil is 1.1 times more than the Young's modulus of the second copper foil (col. 5, lines 9-52).

In re claim 17, **Saida** discloses a process for producing a copper clad laminate, providing an insulation layer constituent material having a first and a second side (col. 1, lines 10-45 and col. 5, lines 43-60), coating the first side with a first copper foil of a first thickness (12 μm , col. 5, lines 9-16), coating the second side with a second copper foil of a second thickness (35 μm , col. 5, lines 43-52) to produce an insulation layer constituent material, first copper foil and second copper foil assembly (col. 5, lines 43-52), wherein the thickness of the second foil is greater than the thickness of the first foil (col. 5, lines 9-16 and col. 5, lines 43-52), hot pressing the assembly to produce the laminate (col. 5, lines 43-52), wherein the first and second copper foils contract during hot pressing, wherein the second copper foil contracts to a larger extent than the first copper foil during hot pressing (col. 1, lines 10-54).

In re claim 18, **Saida** discloses that the thickness of the second foil (35 μm , col. 6, lines 15-32) is four times or less than the thickness of the first foil (12 μm , col. 5, lines 9-16).

In re claim 19, **Saida** discloses that the insulation layer constituent material is a resin (col. 4, lines 57-64).

In re claim 22, Saida discloses that, after hot pressing the Young's modulus of the first copper foil is 1.1 times more than the Young's modulus of the second copper foil (col. 5, lines 9-52).

Claim Rejections - 35 USC § 103

The following is a quotation of 35 U.S.C. 103(a) which forms the basis for all obviousness rejections set forth in this Office action:

(a) A patent may not be obtained though the invention is not identically disclosed or described as set forth in section 102 of this title, if the differences between the subject matter sought to be patented and the prior art are such that the subject matter as a whole would have been obvious at the time the invention was made to a person having ordinary skill in the art to which said subject matter pertains. Patentability shall not be negated by the manner in which the invention was made.

Claims 8, 9, 14, 15, 20 and 21 are rejected under 35 U.S.C. 103(a) as being unpatentable over Saida et al. (U.S. Patent 5,674,611).

In re claims 8, 14, and 20, Saida discloses that the second copper foil contracts at a certain percentage under pressing conditions of 170° C and 60 minutes (col. 5, lines 43-52) but does not explicitly disclose that the second copper foil contracts about 0.05% under pressing conditions of 180° C and 1 hr.

However, there is no evidence indicating the contracts percentage and the pressing conditions range of the second copper foil is critical and it has been held that it is not inventive to discover the optimum or workable percentage/range of a result-effective variable within given prior art conditions by routine experimentation. See MPEP § 2144.05. Note that the specification contains no disclosure of either the critical nature of the claimed dimensions of any unexpected results arising there from. Where patentability is aid to be based upon particular chosen dimensions or upon another

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variable recited in a claim, the Applicant must show that the chosen dimensions are critical. In re Woodruff, 919 F.2d 1575, 1578, 16 USPQ2d 1934, 1936 (Fed. Cir. 1990).

In re claims 9, 15, and 21, it is well-known to one of ordinary skill in the art at the time of the invention was made that the second copper foil may be a S-HTE foil.

Conclusion

Any inquiry concerning this communication or earlier communications from the examiner should be directed to Khiem D. Nguyen whose telephone number is (571) 272-1865. The examiner can normally be reached on Monday-Friday (8:30 AM - 5:30 PM).

If attempts to reach the examiner by telephone are unsuccessful, the examiner's supervisor, Olik Chaudhuri can be reached on (571) 272-1855. The fax phone number for the organization where this application or proceeding is assigned is 703-872-9306.

Information regarding the status of an application may be obtained from the Patent Application Information Retrieval (PAIR) system. Status information for published applications may be obtained from either Private PAIR or Public PAIR. Status information for unpublished applications is available through Private PAIR only. For more information about the PAIR system, see <http://pair-direct.uspto.gov>. Should you have questions on access to the Private PAIR system, contact the Electronic Business Center (EBC) at 866-217-9197 (toll-free).

K.N.
June 06th, 2005



W. DAVID COLEMAN
PRIMARY EXAMINER